**MS10G (E) Package Outline Drawing**

### Package Information

<table>
<thead>
<tr>
<th>Part Number Suffix</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking [3][4]</th>
</tr>
</thead>
<tbody>
<tr>
<td>MS10G</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1 [1]</td>
<td>HNNN XXXX</td>
</tr>
<tr>
<td>MS10GE</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1 [2]</td>
<td>HNNN XXXX</td>
</tr>
</tbody>
</table>

1. Max peak reflow temperature of 235 °C
2. Max peak reflow temperature of 260 °C
3. 4-Digit lot number XXXX
4. 3-Digit part number NNN
Suggested MS10G (E) PCB Land Pattern

NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.